



## Schedule of Scope to Certificate of Approval

### Independent Testing Laboratory

IECQ Certificate No.: IECQ-L CEP 24.0001-01

CB Certificate No.: IECQ-L 2024.006

Schedule Number: IECQ-L CEP 24.0001-01-S

Rev No.: 4

Revision Date: 2025/08/22

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№	Products, Materials	Items,Parameter		Title, Code of specification, standard or method used
		№	Items,Parameter	
1	Electrical and electronic products/electronic semiconductor products	1	Steady-State Temperature-Humidity test	《Environmental testing of electrical and electronic products - Part 2: Test methods - Test Cab: Constant damp heat test》 GB/T 2423.3-2016 《Environmental testing of electrical and electronic products - Part 2: Test methods - Test Cy: Constant wet heat is mainly used for accelerated testing of components》 GB/T 2423.50-2012
		2	Temperature cycle test	《Environmental tests - Part 2: Test methods - Test N: temperature change》 GB/T 2423.22-2012
		3	Temperature storage test	《Environmental testing for electrical and electronic products - Part 2: Test methods - Test A: Low temperature》 GB/T 2423.1-2008
				《Environmental testing for electrical and electronic products - Part 2: Test methods - Test B: High temperature》 GB/T 2423.2-2008
		4	Visual inspection of appearance	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 2009.2
		5	Decap	Methods for destructive physical analysis of military electronic components GJB-4027B-2021 in 1103 in 2.6.2
		6	Delayer	Test Methods and Procedures for Microelectronic Devices GJB-548C-2021 Method 5003 in 3.3.3
		7	IV CURVE	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 5003 in 3.2.3.3.2.4
		8	InGaAs/OBRICH	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 5003 in 3.4(d)
		9	PROBE	Test Methods and Procedures for Microelectronic Devices GJB-548C-2021 Method 5003 in 3.2.12
2	Nonhermetic Surface Mount Devices /Electronic Semiconductor Products	1	Pre-condition test	《Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing》 JSED22-A1131-2020 Clause5
				《Moisture/Reflow Sensitivity Classification for Non-hermetic Surface Mount Devices (SMDs)》 J-STD-020F-2022 Clause5
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J
				《Failure Mechanism Based Stress Test Qualification For Discrete Semiconductors》 AEC-Q101-REV-E
		2	Temperature and humidity bias test	《Steady-State Temperature-Humidity Bias Life Test》 JESD22-A101D.01-2021 Clause4

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# IEC QUALITY ASSESSMENT SYSTEM (IECQ)

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		3	High temperature bias test	《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J
				《Temperature, Bias, and Operating Life》 JESD22-A108G-2022 Clause4
		4	High temperature storage test	《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J
				《High Temperature Storage Life》 JESD22-A103E.01-2021 Clause4
		5	High acceleration stress test	《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J
				《Accelerated Moisture Resistance - Unbiased HAST》 JESD22-A118B.01-2021 Clause4
				《Highly Accelerated Temperature and Humidity Stress Test (HAST)》 JESD22-A110E.01-2021 Clause4
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J
		6	Autoclave test	《Failure Mechanism Based Stress Test Qualification For Discrete Semiconductors》 AEC-Q101-REV-E
				《Accelerated Moisture Resistance - Unbiased Autoclave》 JESD22-A102E-2015 Clause4
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J
		7	Temperature cycle test	《Failure Mechanism Based Stress Test Qualification For Discrete Semiconductors》 AEC-Q101-REV-E
				《Temperature Cycling》 JESD22-A104F.01-2023 Clause4, B,C
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J

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IECQ-L Schedule of Scope Rev. 01